Product Change Notification: ALAN-15XDFJ812

Date:

06-Jun-2025

Product Category:

Inductive Position Sensors

Notification Subject:

CCB 7159 Final Notice: Qualification of 8008MD as a new die attach material for selected LX34070, LX3302A, LX34050 and LX34311 device families available in 14L TSSOP (4.4mm) package.

Affected CPNs:

ALAN-15XDFJ812_Affected_CPN_06062025.pdf
ALAN-15XDFJ812_Affected_CPN_06062025.csv

PCN Status: Final Notification

PCN Type: Manufacturing Change

Microchip Parts Affected: Please open one of the files found in the Affected CPNs section.
Note: For your convenience Microchip includes identical files in two formats (.pdf and .xls)

Description of Change: Qualification of 8008MD as a new die attach material for selected LX34070, LX3302A, LX34050 and LX34311 device families available in 14L TSSOP (4.4mm) package.

Pre and Post Summary Changes:

	Pre Change	**Post Change**
Assembly Site	Microchip Technology Thailand (Branch) (MMT)	Microchip Technology Thailand (Branch) (MMT)
Wire Material	Au	Au
Die Attach Material	2200D	8008MD
Molding Compound Material	G600V	G600V

Lead-Frame Material	C7025	C7025

Impacts to Datasheet: None

Change Impact: None

Reason for Change: To improved manufacturability by qualifying 8008MD as a new die attach material.

Change Implementation Status: In Progress

Estimated First Ship Date: 15 July 2025 (date code: 2529)

Note Below EFSD: Note: Please be advised that after the estimated first ship date customers may receive pre and post change parts.

Timetable Summary:

	September 2024					>	**June 2025**				**July 2025**				
Work Week	36	37	38	39	40		23	24	25	26	27	28	29	30	31
Initial PCN Issue Date			X												
Qual Report Availability							X								
Final PCN Issue Date							X								
Estimated Implementation Date													X		

Method to Identify Change: Traceability Code

Qualification Report: Please open the attachments included with this PCN labeled as PCN_#_Qual_Report.

Revision History: September 18, 2024: Issued initial notification.
September 19, 2024: Re-issued initial PCN to correct the die attach pre-change material from 3280 to 2200D.
November 08, 2024: Re-issued initial PCN to update affected parts list to add CPN LX3302AQPW-TR-C01 and remove LX34211QPW-TR, LX34211QPW-TR-VAO, LX3301AQPW and LX3301AQPW-

TR catalog part numbers. Revised "Notification Subject", "Description of Change" and “Qualification Plan” title to reflect the removed parts numbers. Updated Pre and Post Change Summary table to include Lead-frame paddle size and DAP Surface Prep. Added Pre and post change comparison for the Lead-frame drawing.
February 19, 2025: Re-issued initial PCN. Updated Pre and Post Change Summary table by removing the Lead-frame paddle size and DAP Surface Prep, as there no changes to these. Removed Pre and post change comparison for the Lead-frame drawing. Updated the affected parts list.
June 06, 2025: Issued final notification. Attached the Qualification Report. Provided estimated first ship date to be on July 15, 2025.

Note: The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable product.

Attachments:

PCN_ALAN-15XDFJ812_Qual_Report.pdf

Please contact your local **Microchip sales office** with questions or concerns regarding this notification.

Terms and Conditions:

Affected Catalog Part Numbers (CPN)

LX3302AQPW

LX3302AQPW-EASY

LX3302AQPW-TR

LX3302AQPW-TR-C01

LX3302AQPW-TR-EASY

LX3302AQPW-TR-GM

LX34050QPW

LX34050QPW-TR

LX34050QPW-TR-VAO

LX34050QPW-VAO

LX34070AT-H/ST

LX34070AT-H/STVAO

LX34070-H/ST

LX34070-H/STVAO

LX34070T-H/ST

LX34070T-H/STVAO

LX34311T-H/ST

LX34311T-H/STVAO